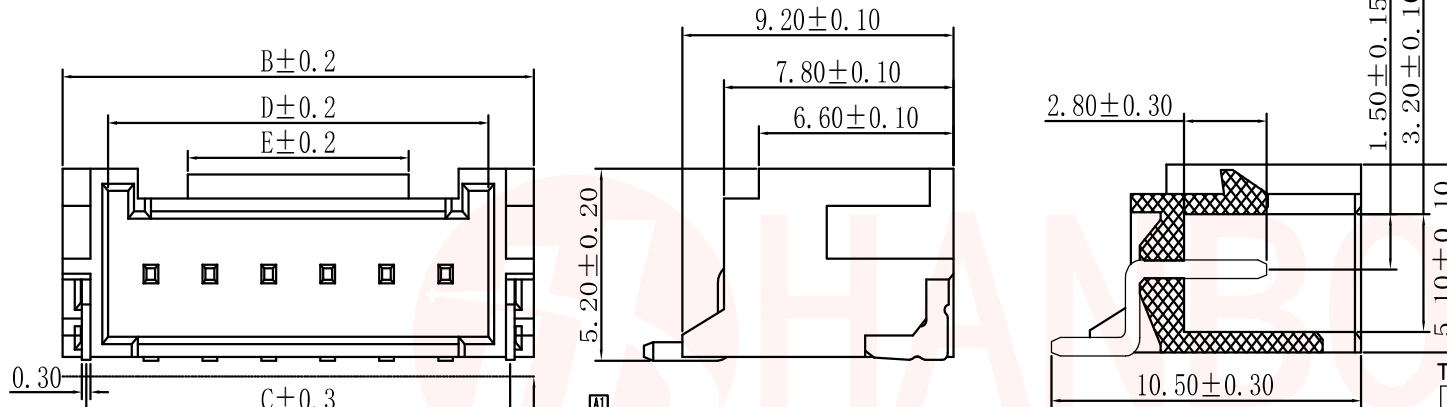




REV.	ECN NO OR DESCRIPTION	REVISED	DATE

SPECIFICATIONS

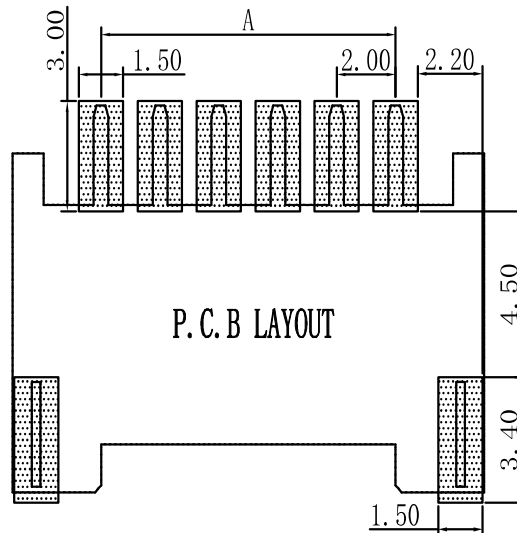
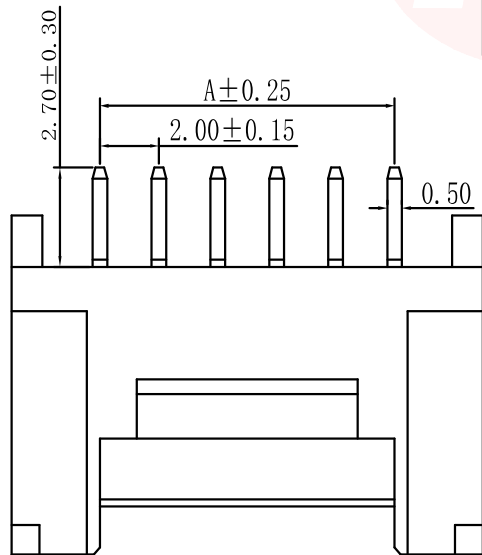
- 1、Current Rating: 2A AC, DC
- 2、Voltage Rating: 250V AC, DC
- 3、Temperatuer Range: -25°C~+85°C
- 4、Contact Resistance: 20mΩ Max
- 5、Insulation Resistance: 1000MΩ Min
- 6、Withstanding Voltang: 1000V AC/minute
- 7、Material: Wafer LCP, UL94V-0
PIN Brass Tin-plated
Solder tad Brass Tin-plated



Material	Part No.	Thickness	Max
Al	02P-10P	0.10	MAX
Al	11P-16P	0.12	MAX

TABLE:

CSG PART NO.	Dimension mm				
	A	B	C	D	E
WAFER-HY200W-2A	2.00	8.00	6.50	4.90	2.50
WAFER-HY200W-3A	4.00	10.00	8.50	6.90	3.00
WAFER-HY200W-4A	6.00	12.00	10.50	8.90	5.00
WAFER-HY200W-5A	8.00	14.00	12.50	10.90	7.00
WAFER-HY200W-6A	10.00	16.00	14.50	12.90	9.00
WAFER-HY200W-7A	12.00	18.00	16.50	14.90	11.00
WAFER-HY200W-8A	14.00	20.00	18.50	16.90	13.00
WAFER-HY200W-9A	16.00	22.00	20.50	18.90	15.00
WAFER-HY200W-10A	18.00	24.00	22.50	20.90	17.00
WAFER-HY200W-11A	20.00	26.00	24.50	22.90	19.00
WAFER-HY200W-12A	22.00	28.00	26.50	24.90	21.00
WAFER-HY200W-13A	24.00	30.00	28.50	26.90	23.00
WAFER-HY200W-14A	26.00	32.00	30.50	28.90	25.00
WAFER-HY200W-15A	28.00	34.00	32.50	30.90	27.00
WAFER-HY200W-16A	30.00	36.00	34.50	32.90	29.00



UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.25	X :±2°
X.X :±0.20	X.X :±1°
X.XX :±0.15	



东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	WAFER HY 2.0 贴片带卡扣 SMT TYPE			
DWN	xiong	PART NO.	WAFER-HY200W-NA	
CHKD	lee	SCALE: 1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET: 10F 1	REV: A4

CUSTOMER COPY